





Electrical Specifications:

Parameter	Symbol	Min.	Тур.	Max.	Units	Conditions
Frequency of Operation	Fo		156.250000		MHz	
		Fre	quency Stabil	ity		
Frequency Stability	ΔF/F	-50		+50	ppm	Includes initial tolerance @ +25°C, deviation over operating temperature, variations to supply voltage, load, vibration and shock.
Aging		-5		+5	ppm	1 st year
			RF Output			
Output Type		Ľ	VDS Compatible	Э		
Output Load		1	00 Ω Differentia		V	
Symmetry (duty cycle)	V _{OH}	45		55	%	Ref. to 50% of waveform
Differential Output Voltage	Vdiff	250	350	450	mV	peak-to-peak differential output voltage
Logic "1" Level	V _{OH}	1.375			V	
Logic "0" Level	V _{OL}			1.125	V	
Rise/Fall Time	T _R /T _F		0.2	0.4	nS	20% to 80% of waveform
Start-up Time	Ts∪			10	mS	T _{ambient} = +25°C
	S	upply Volta	ge & Power C	onsumptio	n	
Operating Voltage	Vcc	3.135	3.3	3.465	V	
Supply Current	lcc		25	45	mA	
		Ot	ther Parameters		•	
Phase Jitter (RMS)	ΦJ			0.150	pS	12KHz to 20MHz

Enable/Disable Function:

Pad 1	Output Pad #4, #5
High or Open	
0.7Vcc Min	Output Enabled
0.3 Vcc Max	Output Disabled to high-Z

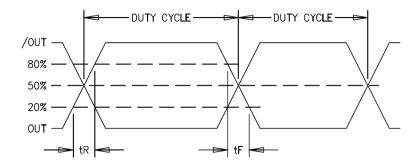
Enable Phase Delay = 2.0 mSec Max Disable Phase Delay = 200 nSec Max







Output Waveform:



Environmental & Packaging Requirements:

Operating Temperature	TA	-40		+85	°C	
Storage Temperature	Ts	-55		+125	°C	
Mechanical Shock	Per MIL-STD-202, Method 213, Condition C (100 g's, 6 ms duration, 1/2 sinewave)			duration, ½ sinewave)		
Vibration		Per MIL-STD-202, Method 201 & 204 (10 g's from 10-2000 Hz)				
Thermal Cycle	Per MIL-STD-883, Method 1010, B (-55°C to 125°C, 15 min. dwell, 10 cycles)					
Hermeticity	Per MIL-STD-202, Method 112 (1 x 10 ⁻⁸ atm cc/s of Helium)					
Moisture Sensitivity Level (MSL)	MSL 1					
Solderability	Per EIAJ-STD-002					
Max. Soldering Conditions	See solder profile, Figure 1					
Package Type	6-pad 3.2	X 5.0 X 1.4	I mm leadless	ceramic. Ro	oHS compliar	nt.

Marking, Pin Out:

Pad	Function
1	Enable/Disable
2	N/C
3	Ground
4	Output
5	Complimentary Output
6	+V _{cc}

Part Marking		
Line 1	156M250	
Line 2	M (yy ww vv)	

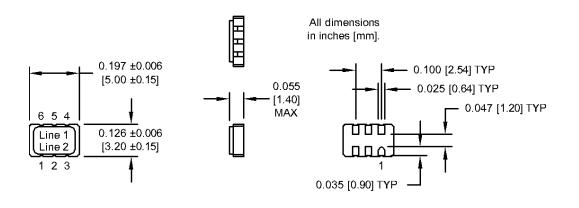
Legend			
уу	Year		
ww	Work Week		
vv	Factory code		

Dimensions:

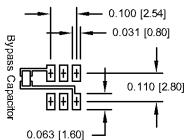




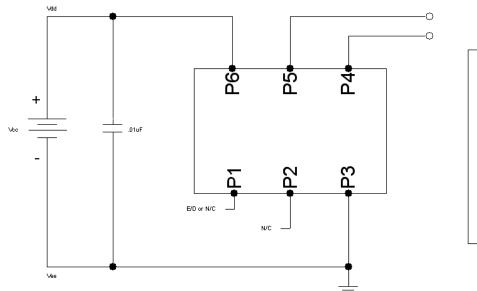


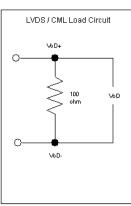


SUGGESTED SOLDER PAD LAYOUT



Typical Test Circuit & Load Circuit Diagrams:





Soldering Conditions:







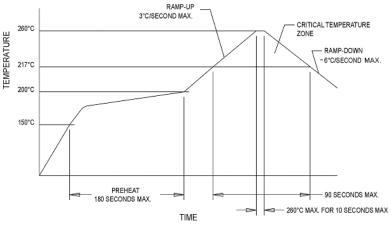
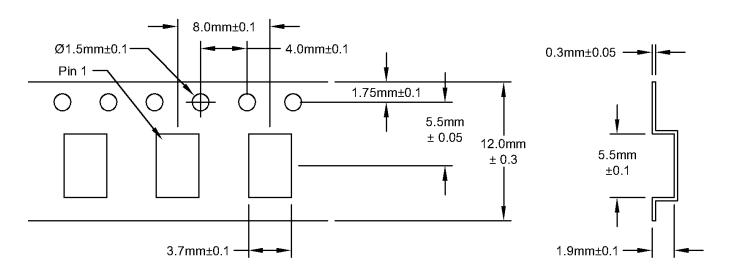


Figure 1

Tape and Reel Specifications:



Datasheet Revision Table:

Date	Rev.	Author	Details of Revision
03/31/15	0	MM	Original release.
05/10/16	А	MM	Updated supply current specification.